

Si-Pad Press Pad

Description:

Si-Pad is a fiberglass reinforced, cured silicone rubber press pad.

Suggested Applications:

Use Si-Pad in the lamination press as a pressure equalizer / heat lagging material during the manufacturer of rigid, rigid-flex and flexible printed circuit boards.

Technical Data:

Maximum Use Temperature:	500°F / 260°C
Thickness:	.060" / 1.6 mm
Elongation:	N/A
Color:	Red

Features / Benefits:

Si-Pad is a multi-cycle product allowing for use through many repetitive press cycles with minimal degradation of its mechanical properties.

Related Airtech Products:

Dahlar high temperature release films

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